

SMT current sense transformers

EP10 Core

Series/Type: B78419

Date: March 2023

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Construction

- Ferrite core
- Primary winding: frame molded in
- Secondary winding: copper wire
- Creepage distance Np/(Ns, core) 6 mm
- Clearance distance Np/Ns (CuL) 3.5 mm
- Clearance distance Np/core 5.3 m
- Plastic bobbin (UL94-V0, CTI ≥ 175)

Features

- Very low DC resistance
- Different turn ratios
- Small SMD package
- RoHS compatible
- Qualified to AEC-Q200
- Design complies with IEC 61558-2-16 (Basic insulation, working voltage RMS 500 V)
- Insulation distances in compliance with IEC 60664 (Basic insulation, working voltage RMS 500 V)
- UL 1446 Class 155 (F) electrical insulation system UL 1446 Class 155 (F) electrical insulation system

Applications

- Switch-mode power supplies
- Feedback control
- Overload sensing
- Load drop/shut down detection

Terminals

■ L-Pins

Marking

 Product brand, middle block of ordering code, date code, pin 1 marker, production place identification code
 Minimum data on packaging:
 Manufacturer's logo, ordering code, quantity, date code

Delivery mode and packing units

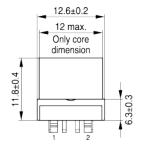
- Blister tape
- Packing unit: 200 pcs.

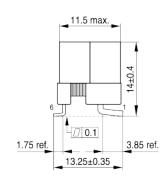




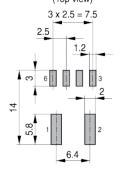
Dimensional drawing

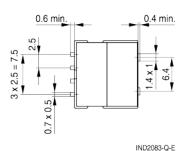
EP10 Core



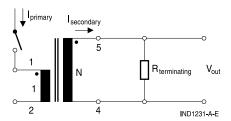


Recommended PCB layout (Top view)





Application circuit and pinning





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EP10 Core	

Technical data and measuring conditions

All data is specified at $\pm 25~^{\circ}\text{C}$ if not mentioned otherwise. All values without tolerance are typical values.

Typical frequency range	50 250 kHz
High voltage	2400 V AC, 50 Hz, 1 s (winding to winding) Type test 60 s
Inductance L (5-4)	Measured at 20 kHz, 10 mV, +25 °C
DC resistance R _{max} (1-2)	Measured at +25 °C
DC resistance R _{max} (5-4)	Measured at +25 °C
Sensed current: I _{prim,RMS}	The max. input current of 30 A causes approx. +40 °C tempera-
,	ture rise
Couple capacitance C _p (1-5)	Measured at 10 kHz, 1 V, +25 °C
Resistance to reflow soldering	In accordance with JEDEC J-STD-020D +245 °C for 20 seconds
heat	
Operating temperature range	-40 °C +150 °C (component)
Pollution degree	P2 (to IEC 61558-1, 60664)
Insulation thermal class	+155 °C (F) (to IEC 60085)
Weight	Approx. 5 g
Approvals	UL 1446 class 155 (F) (E320370)

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$$B_{max} = \frac{V_{out, max} \cdot \delta_{max}}{N_{s} \cdot A_{e} \cdot f_{osc}}$$

With:

B_{max} Maximum magnetic flux density in the ferrite core of the current sense

transformer

V_{out max} Maximum output voltage of the measurement signal

 δ_{max} Maximum duty cycle

N_s Number of turns of the secondary winding of the current sense transformer

A_e Effective magnetic area of the ferrite core

f_{osc} Operating frequency of the switching operator IC

Typical value for A_e : 10.7 x 10⁻⁶ m² Typical B_{max} : < 220 mT

$$R_T = \frac{V_{out, max} \cdot N_s}{I_{IN, max}}$$

With:

R_T Resistance of burden resistor

 $\begin{array}{ll} V_{out,max} & \quad \text{Maximum output voltage of the measurement signal} \\ N_s & \quad \text{Number of turns of the secondary side of the CST} \end{array}$

I_{IN.max} Maximum input current (peak current)

Characteristics and ordering codes

L _{min} (5-4)	Turns ratio	Voltage time product +120 °C ¹⁾	C _p	R _{max} (1-2)	R _{max} (4-5)	Recommended	Ordering code
mΗ	N _p : N _s	mA	pF	Ω	Ω	R _T ²⁾	
1.7	1:50	117	4	0.5	1.5	1.6	B78419A2288A003
3.0	1:70	164	4	0.5	2.1	2.3	B78419A2289A003
7.0	1:100	235	4	0.5	3.1	3.3	B78419A2251A003
11.0	1:125	294	4	0.5	4.0	4.1	B78419A2290A003
25.0	1:180	423	4	0.5	7.4	6.0	B78419A2271A003

The maximum volt-sec rating limits the peak flux density to 220 mT when used in a unipolar drive application.
For bipolar drive applications, a maximum volt-sec of two times is acceptable.

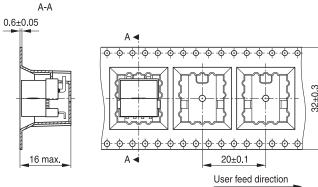
Burden Resistor value is calculated by taking V_{out} as 1 V reference and with maximum input current flowing through the input (30 A).

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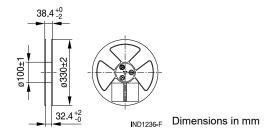
Taping and packing

Blister tape



IND2055-Y-E Dimensions in mm

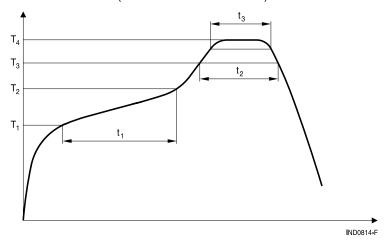
Reel



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Recommended reflow soldering curve

Pb-free solder material (based on JEDEC J-STD 020E)



T ₁	T ₂	T ₃	T ₄	t ₁	t ₃	t ₃
°C	°C	°C	°C	sec	sec	sec
150	200	217	245	60 – 120	60 – 150	< 30 @ T ₄ – 5 °C

Time from 24 °C to T₄: max. 480 s Maximal numbers of reflow cycles: 3

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Cautions and warnings

- Please note the recommendations in our Inductors data book (latest edition), online catalogs and in the data sheets.
 - Particular attention should be paid to the derating curves, if given. Derating applies in the case
 the ambient temperature in application exceeds the rated temperature of the component.
 - Ensure the operation temperature of the component in application, not to exceed the maximum specified value or the upper climatic category temperature.
 - The soldering conditions should also be observed. Temperatures quoted in relation to wave soldering refer to the pin, not the housing.
- If the components are to be washed varnished it is necessary to check whether the washing varnish agent that is used has a negative effect on the wire insulation, any plastics that are used, or on glued joints. It is possible for washing varnish agent residues to have a negative effect in the long-term on wire insulation.
 - Washing processes may damage the product due to the possible static or cyclic mechanical loads (e.g., ultrasonic cleaning). They may cause cracks to develop on the product and its parts, which might lead to reduced reliability or lifetime.
- The following points must be observed if the components are potted, sealed, or varnished in customer applications:
 - Many potting, sealing of varnishing materials shrink as they harden. They therefore exert a
 pressure on the plastic housing or core. This pressure can have a deleterious effect on electrical properties, and in extreme cases can damage the core or plastic housing mechanically.
 - It is necessary to check whether the potting, sealing or varnishing materials used attacks or destroys the wire insulation, plastics, or glue.
 - The effect of the potting, sealing, or varnishing materials may change the high-frequency behavior of the components.
- Magnetic core materials such as ferrites are sensitive to direct impact. This can cause the core material to flake or lead to breakage of the magnetic core material.
- Any type of tension or pressure on the product may result in damage and affect its functionality and reliability.
 - The products are only to be attached to fixings or mounting holes provided for this purpose in accordance with the data sheet.
 - If additional mechanical forces are applied to the component, e.g., application of gap pads, it
 is necessary to check whether they attack or destroy any part of the component.
 - It is not permitted for the product specified in the data sheet to assume a mechanical function in the final application.
- Inductance value can drop if external metallic or magnetic parts will be put close to the coil or into the air gap of the coil or core or magnetic material.
- Even for customer-specific products, conclusive validation of the component in the circuit can only be carried out by the customer.

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Release 2022-07